



# 8 (NE)  
42403  
MULLISL  
AF  
2800

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s)	Wang	Examiner:	Warren, Matthew E.
Serial No.:	10/057,448	Group Art Unit:	2815
Confirmation No.:	1290	Docket:	669-77 CON
Filed:	January 25, 2002	Dated:	April 14, 2003
For:	HIGH DENSITY INTEGRATED CIRCUITS AND THE METHOD OF PACKAGING THE SAME		

Commissioner for Patents  
Washington, DC 20231

*I hereby certify this correspondence is being deposited  
with the United States Postal Service as first class mail,  
postpaid in an envelope, addressed to:  
Commissioner for Patents, Washington, D.C. 20231*

On: April 14, 2003

By: Amanda F. Shaw  
Amanda F. Shaw

RESPONSE PURSUANT TO 37 C.F.R. §1.116

Sir:

In response to the final Office Action mailed January 15, 2003, a reply to which is being filed today, April 14, 2003, please consider the claims of the above-identified application in view of the following remarks.

REMARKS

The application has been amended. Reconsideration of the application in view of the above amendment and the following remarks is respectfully requested.

Claims 15-28 are pending in this application.

RECEIVED  
APR 22 2003  
TECHNOLOGY CENTER 2800